

Requested Patent: JP3169062

Title: SEMICONDUCTOR DEVICE

Abstracted Patent: JP3169062

Publication Date: 1991-07-22

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Application Number: JP19890310161 19891128

Priority Number(s):

IPC Classification: H01L25/065 ; H01L23/50 ; H01L25/07 ; H01L25/18

Equivalents:

ABSTRACT:

PURPOSE: To reduce a package occupation area of a semiconductor device on a circuit board and to improve integration of a circuit board by stacking semiconductor chips solidly.

CONSTITUTION: A first semiconductor chip 1 is mounted on an island 5. An inner lead 6 provided on the periphery of the island 5 and a pad electrode 7 provided on the peripheral edge part of the semiconductor chip 1 are connected by a thin metal wire 4. Then, a second semiconductor chip 2 is mounted which has a bump 3 corresponding to a pad electrode 8 provided inside the pad electrode 7; the pad electrode 8 and the bump 3 are bonded by pressure; and the semiconductor chip 1 and the semiconductor chip 2 are electrically connected. Thereby, it is possible to reduce a package occupation area of a semiconductor device on a circuit board and to improve integration of a circuit board.